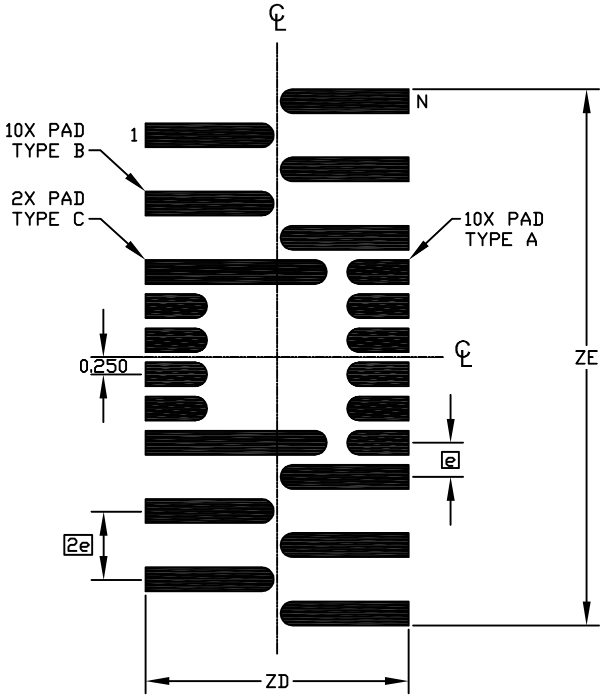
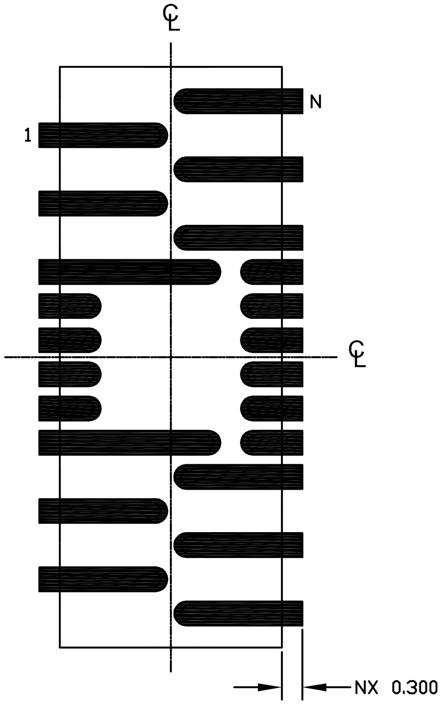
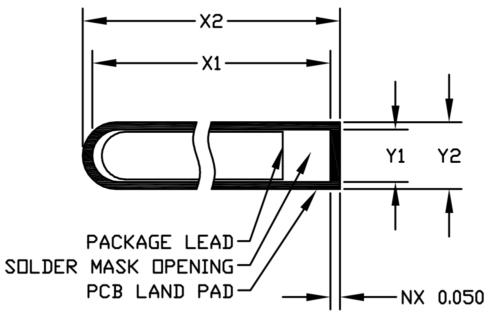
RECOMMENDED LAND PATTERN



PACKAGE OVERLAY



PAD DETAIL INFORMATION



	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
e	0.500 BSC			.020 BSC		
N	22 PINS			22 PINS		
ZD	3.850 REF			.152 REF		
ZE	7.850 REF			.309 REF		

	MILLIMETERS			INCHES		
DIM	TYPE A	TYPE B	TYPE C	TYPE A	TYPE B	TYPE C
Y1	0.275	0.275	0.275	.011	.011	.011
Y2	0.350	0.350	0.350	.014	.014	.014
X1	0.800	1.775	2.550	.031	.070	.100
X2	0.900	1.875	2.650	.035	.074	.104

NOTES:
1. REFERENCE PKG. OUTLINE: 21-1019
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODE ONLY.
4. ALL DIMENSIONS IN MM.

-DRAWING NOT TO SCALE-

This document (including dimensions, notes & specs) is a recommendaton based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use.
This document is subject to change without notice.
Contact technical support at http://www.maximintegrated.com/support for further questions.

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TITLE:
PACKAGE LAND PATTERN,
[P223A8F+1] FCQFN

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